

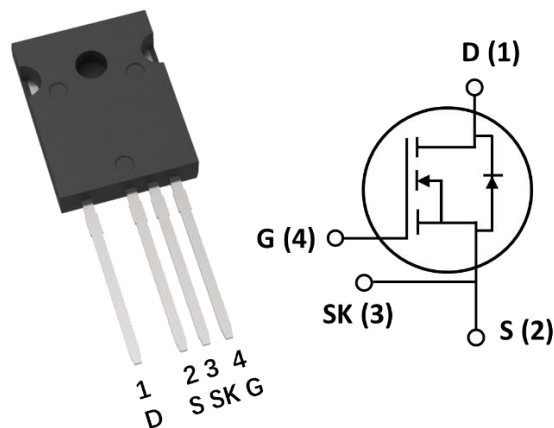
# NW6506CJ1

## 650V N-Channel Silicon Carbide Power MOSFET

Parameter	Value	Unit
$V_{DS}$	650	V
$R_{DS(on)}$	60	m $\Omega$
$I_D$	56	A

### Features

- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery ( $Q_{rr}$ )
- Easy to parallel.
- RoHS compliant



### Applications

- Switch Mode Power Supplies
- DC/DC converters
- Solar inverters
- Battery Chargers
- Motor Drives

### Description

The NW6506CJ1 is a 650V, 60mohm SiC MOSFET designed for improved system efficiency, large power density, and high operating frequency. It reduces cooling requirements and gate ringing while simplifying system complexity. This results in a significant cost reduction, making it an ideal solution for enhancing performance in a wide range of applications.

### Pin Description

Pin No.	Pin Name	Description
1	D	Drain
2	S	Source
3	SK	Kelvin Source
4	G	Gate

## Absolute Maximum Ratings

$T_J = 25\text{ }^\circ\text{C}$  except as noted. Exceeding the maximum ratings may damage the device.

Parameter	Symbol	Value	Unit	Test conditions
Drain-Source Breakdown Voltage	$V_{DSmax}$	650	V	$V_{GS}=0\text{ V}, I_D=100\text{ }\mu\text{A}$
Continuous Drain Current	$I_D$	56	A	$V_{GS}=20\text{ V}, T_C=25\text{ }^\circ\text{C}$
Pulsed Drain Current	$I_{D(pulse)}$	112	A	Pulse width $t_p$ limited by $T_{jmax}$
Power dissipation	$P_D$	259	W	$T_C = 25\text{ }^\circ\text{C}$
Recommend Gate Source Voltage	$V_{GS,op}$	-5/+20	V	
Maximum Gate Source Voltage	$V_{GSmax}$	-10/+25	V	AC ( $f > 1\text{ Hz}$ )
Operating Junction Temperature	$T_J$	-55 to +175	$^\circ\text{C}$	-
Storage Temperature	$T_S$	-55 to +175	$^\circ\text{C}$	-
Soldering Temperature	$T_L$	260	$^\circ\text{C}$	

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{TH,J-C}$	0.59	$^\circ\text{C/W}$

## Electrical Characteristics

### Static Characteristics

Parameters	Symbol	Min	Typ	Max	Unit	Condition
Drain-Source Breakdown Voltage	$BV_{DS}$	650	-	-	V	$V_{GS}=0\text{ V}, I_D=100\text{ }\mu\text{A}$

Zero Gate Voltage Drain Current	$I_{DSS}$	-	10	100	$\mu\text{A}$	$V_{DS}=650\text{ V}, V_{GS}=0\text{ V}$
Gate-Source Leakage	$I_{GSS}$	-	5	250	nA	$V_{GS}=20\text{ V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	2	-	4	V	$I_D=5\text{ mA}, V_{GS}=V_{DS}$
Drain-Source On-Resistance	$R_{DS(on)}$	-	60	80	m $\Omega$	$V_{GS}=20\text{ V}, I_D=13.2\text{ A}$
			80			$V_{GS}=18\text{ V}, I_D=13.2\text{ A}$
			89			$V_{GS}=15\text{ V}, I_D=13.2\text{ A}$

### Dynamic Characteristics

Input Capacitance	$C_{iss}$	-	1129	-	pF	$V_{GS}=0\text{ V}, V_{DS}=600\text{ V}$ $f=1.0\text{ MHz}, V_{AC}=25\text{ mV}$
Output Capacitance	$C_{oss}$	-	114	-		
Reverse Transfer Capacitance	$C_{rss}$	-	6.5	-		
$C_{oss}$ Stored Energy	$E_{oss}$	-	25	-	$\mu\text{J}$	
Total Gate Charge	$Q_g$	-	62	-	nC	$V_{DS}=400\text{ V}$ $I_D=13.2\text{ A}$ $V_{GS}=-5/+20\text{ V}$
Gate-Source Charge	$Q_{gs}$	-	18	-		
Gate-Drain Charge	$Q_{gd}$	-	33	-		
Turn-on Delay Time	$t_{d(on)}$	-	21.3	-	ns	$V_{DS}=400\text{ V}$ $V_{GS}=-5/+20\text{ V}$ $I_D=13.2\text{ A}$ $R_{G(ext)}=2.5\ \Omega$
Turn-on Rise Time	$t_r$	-	14.5	-		
Turn-off Delay Time	$t_{d(off)}$	-	132.6	-		
Turn-off Fall Time	$t_f$	-	42.7	-		
Internal Gate Resistance	$R_{G(int)}$	-	2.8	-	$\Omega$	$f=1.0\text{ MHz}, V_{AC}=25\text{ mV}$

### Body Diode Characteristics

Continuous Diode Forward Current	$I_S$	-	-	56	A	
Diode Forward Voltage	$V_{SD}$	-	3.0	-	V	$V_{GS}=0\text{ V}, I_S=6.6\text{ A}$
Reverse Recovery Time	$t_{rr}$	-	23	-	ns	$I_S=13.2\text{ A}, V_{DS}=400\text{ V}$ $V_{GS}=-5\text{ V}$ $di/dt=2100\text{ A}/\mu\text{s}$
Reverse Recovery Charge	$Q_{rr}$	-	132	-	nC	
Peak Reverse Recovery Current	$I_{rrm}$	-	13	-	A	

## Electrical Performance Graphs

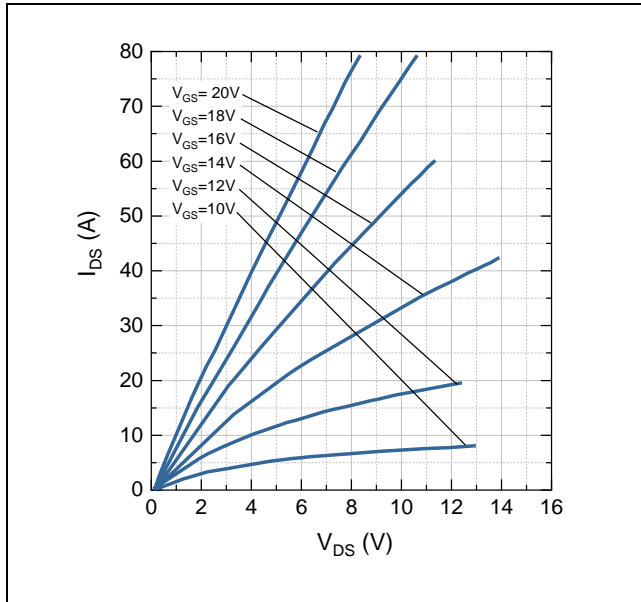


Figure 1: Typical Output Characteristics at  $T_J = -55\text{ }^\circ\text{C}$

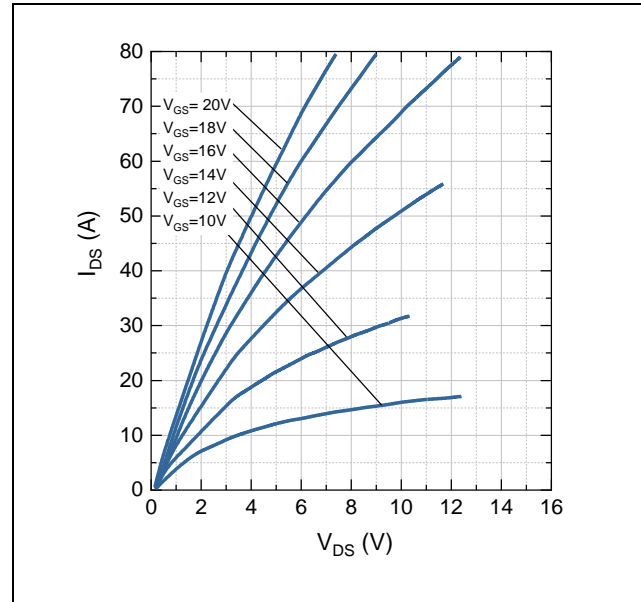


Figure 2: Typical Output Characteristics at  $T_J = 25\text{ }^\circ\text{C}$

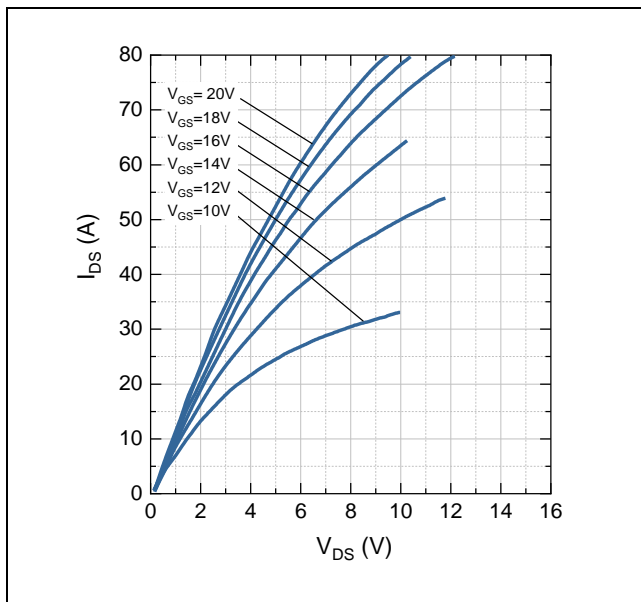


Figure 3: Typical Output Characteristics at  $T_J = 175\text{ }^\circ\text{C}$

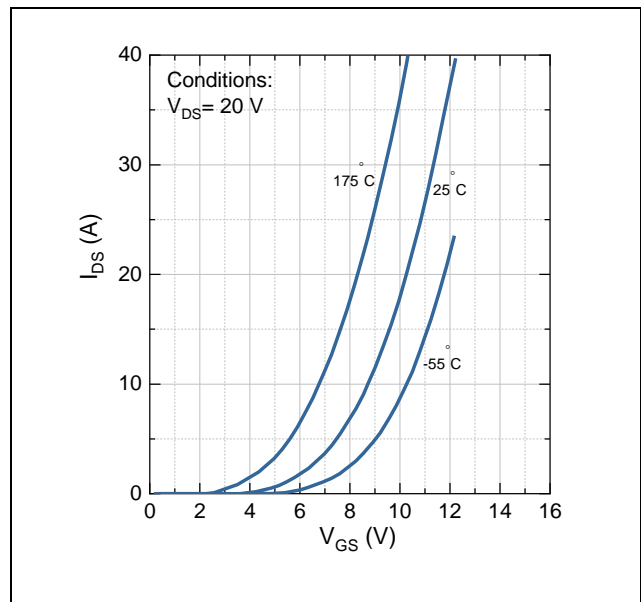


Figure 4: Typical Transfer Characteristics for Various Temperature

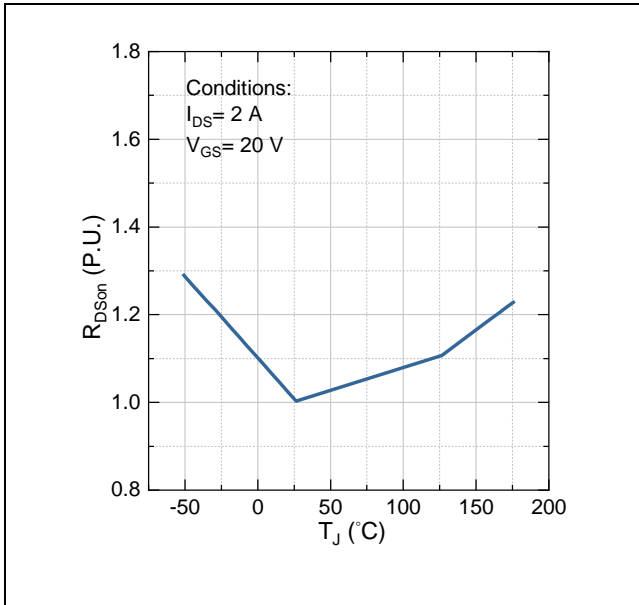


Figure 5: Normalized On-Resistance vs Temperature

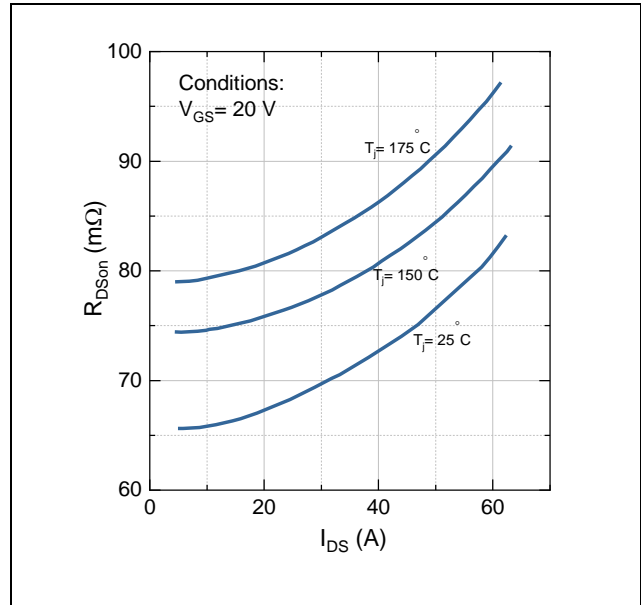


Figure 6: On-Resistance vs. Drain Current for Gate Various Temperatures

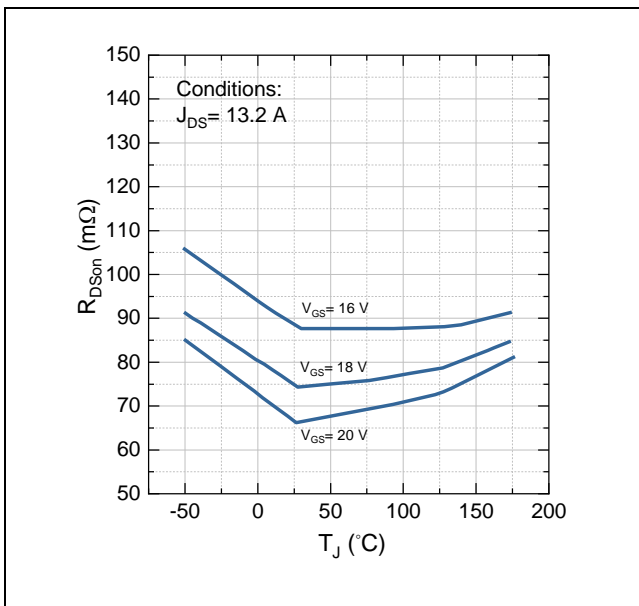


Figure 7: On-Resistance vs. Temperature for Various Voltage

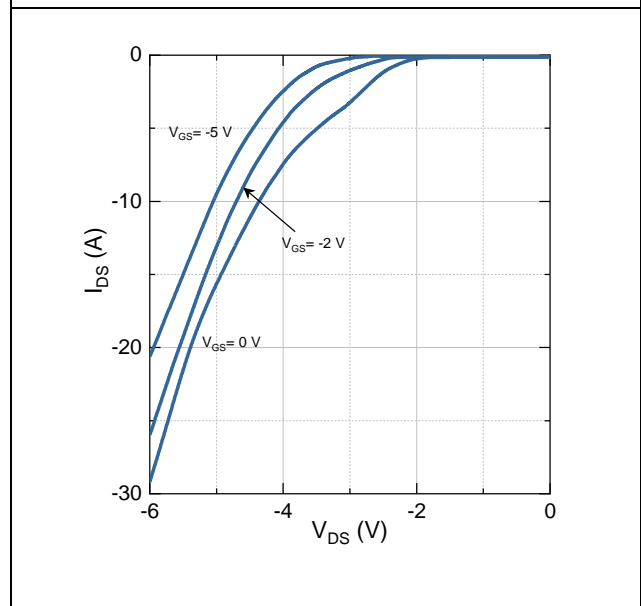


Figure 8: Typical Body Diode Characteristics at  $T_J = -55 \text{ °C}$

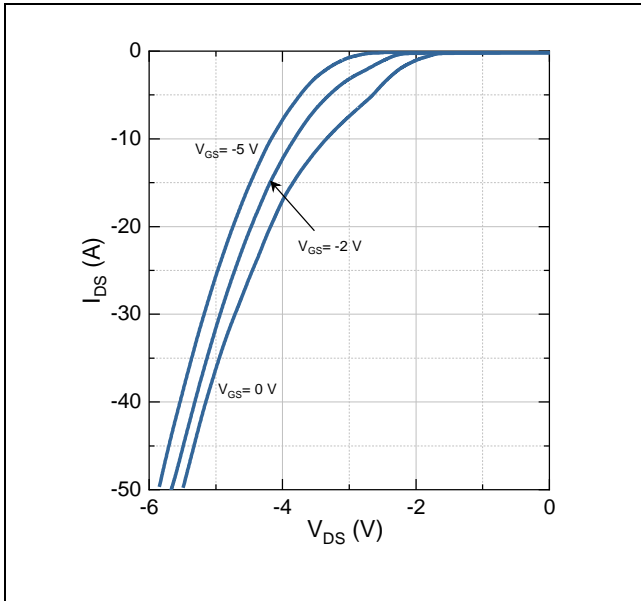


Figure 9: Typical Body Diode Characteristics at  $T_J=25\text{ }^\circ\text{C}$

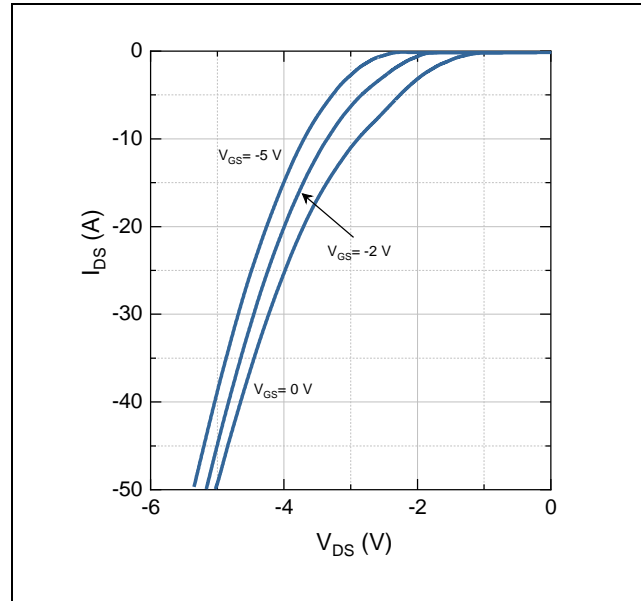


Figure 10: Typical Body Diode Characteristics at  $T_J=175\text{ }^\circ\text{C}$

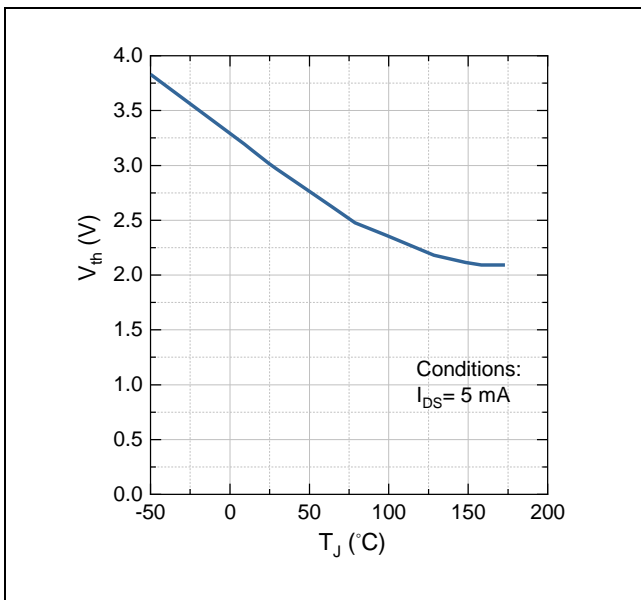


Figure 11: Typical Threshold Voltage vs. Temperature

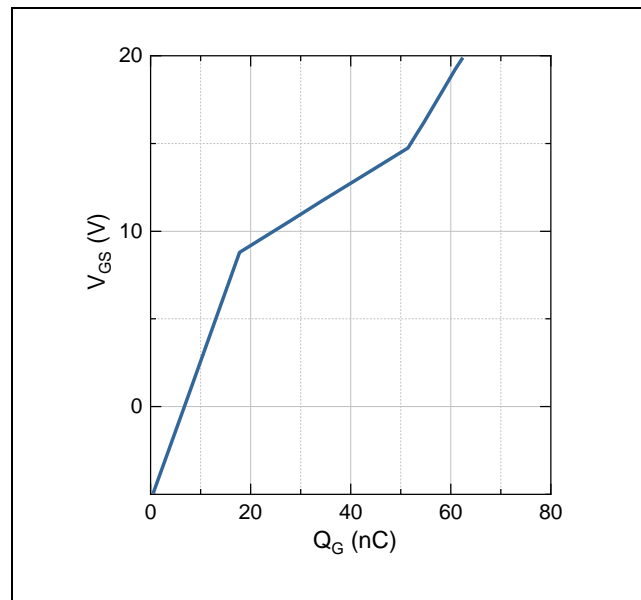


Figure 12: Typical Gate Charge Characteristics at  $T_J=25\text{ }^\circ\text{C}$

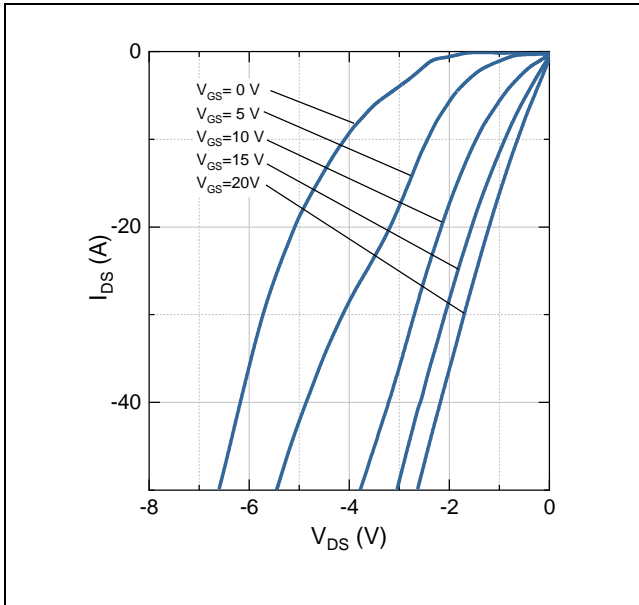


Figure 13: Typical 3<sup>rd</sup> Quadrant Characteristics  $T_J = -55\text{ }^\circ\text{C}$

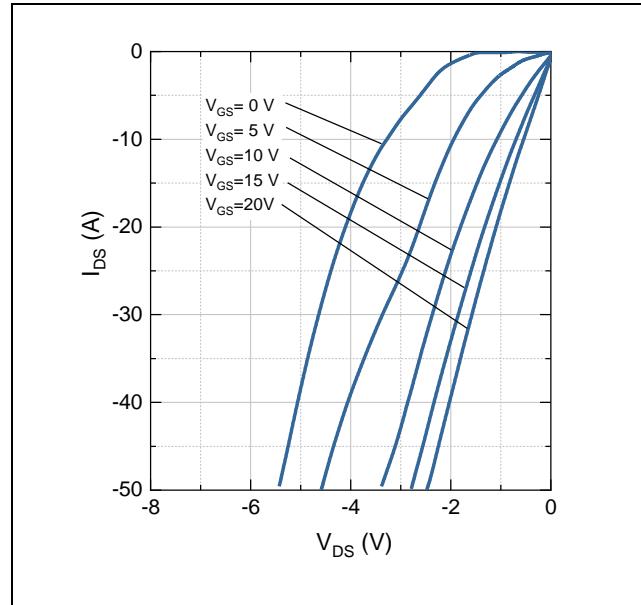


Figure 14: Typical 3<sup>rd</sup> Quadrant Characteristics at  $T_J = 25\text{ }^\circ\text{C}$

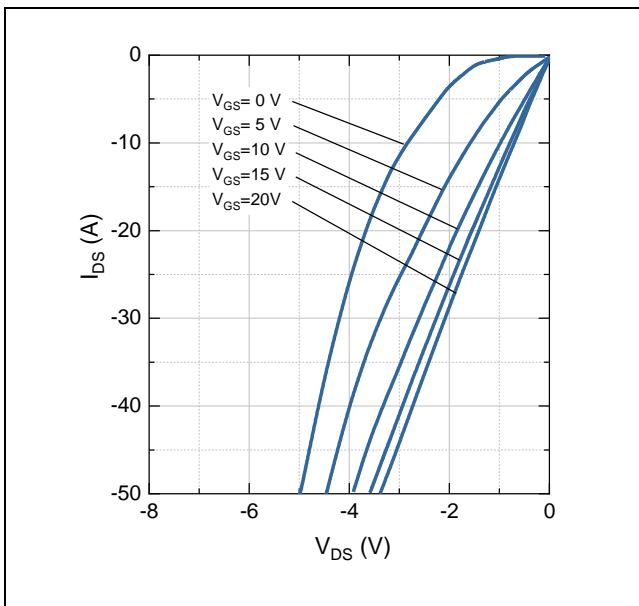


Figure 15: Typical 3<sup>rd</sup> Quadrant Characteristics at  $T_J = 175\text{ }^\circ\text{C}$

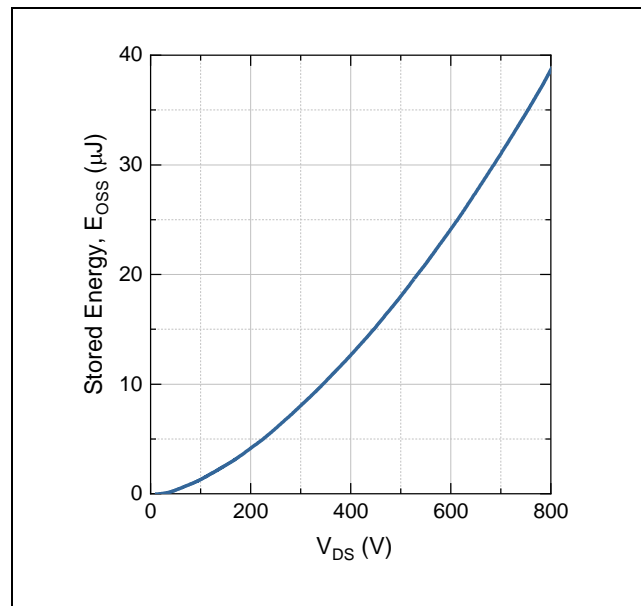


Figure 16: Typical Output Capacitor Stored Energy

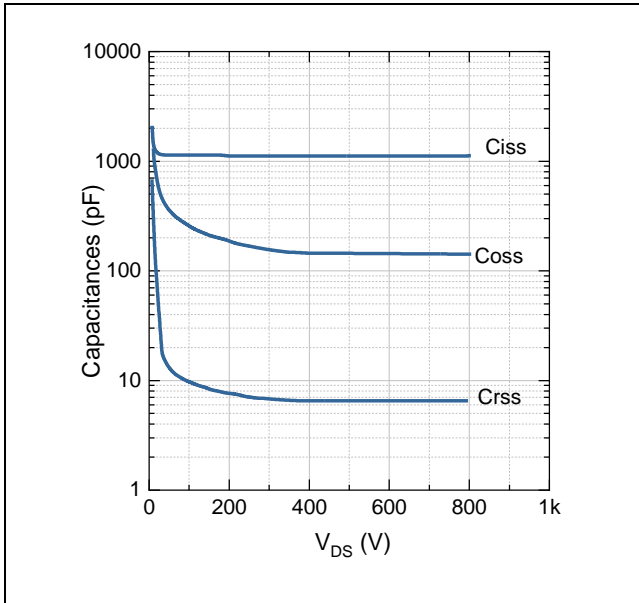


Figure 17: Typical Capacitances vs. Drain-Source Voltage

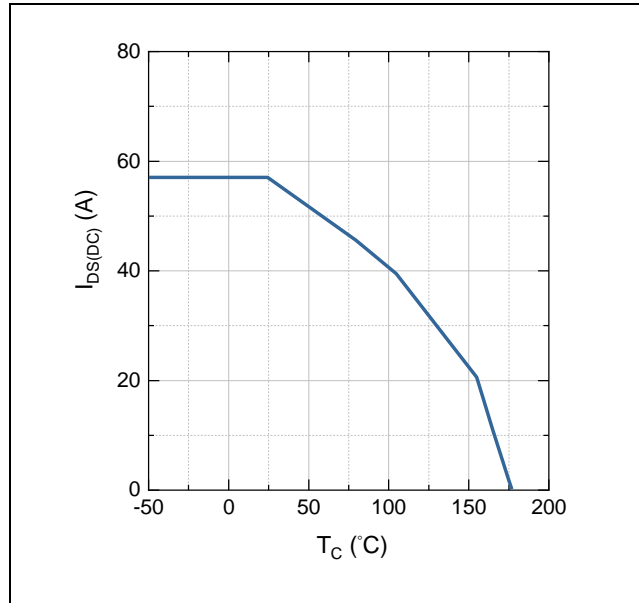


Figure 18: Continuous  $I_{DS}$  Current Derating Curve

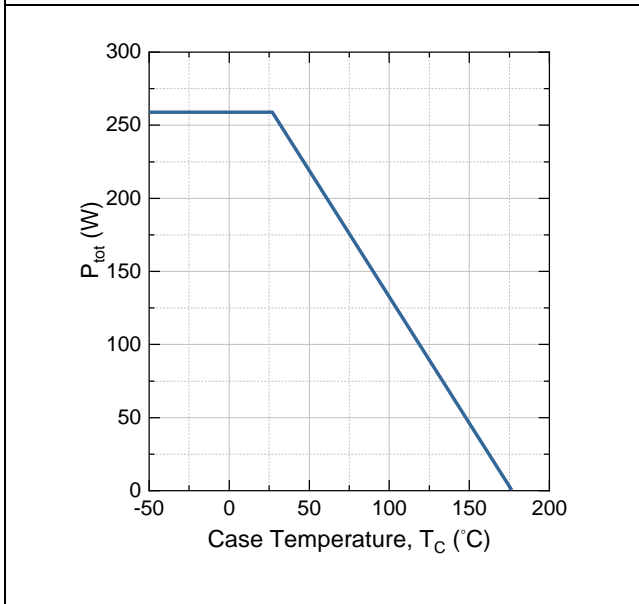


Figure 19: Power Dissipation Derating Curve

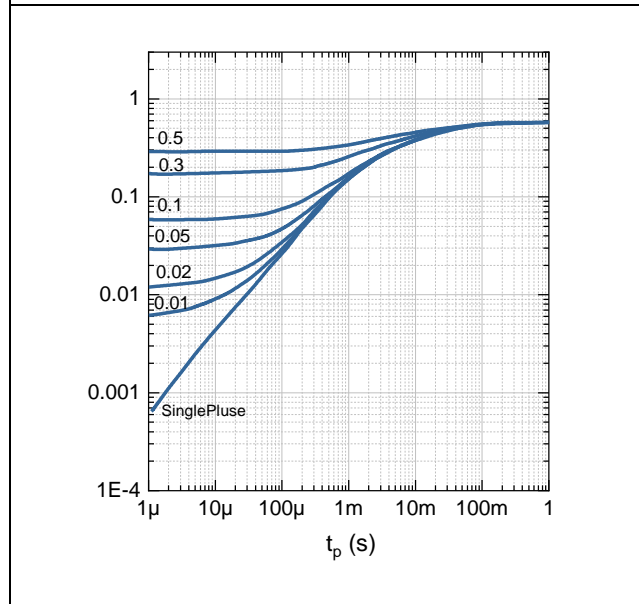


Figure 20: Typical Transient Thermal Impedance (Junction- Case) with Duty Cycle

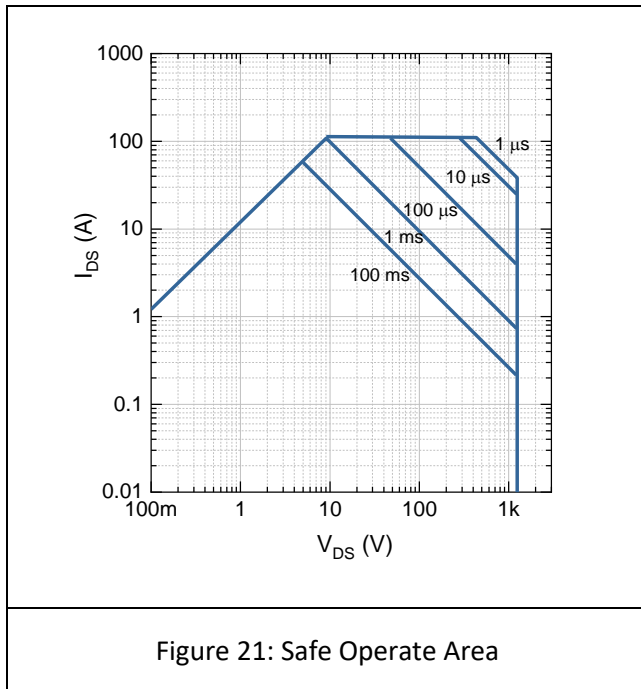


Figure 21: Safe Operate Area

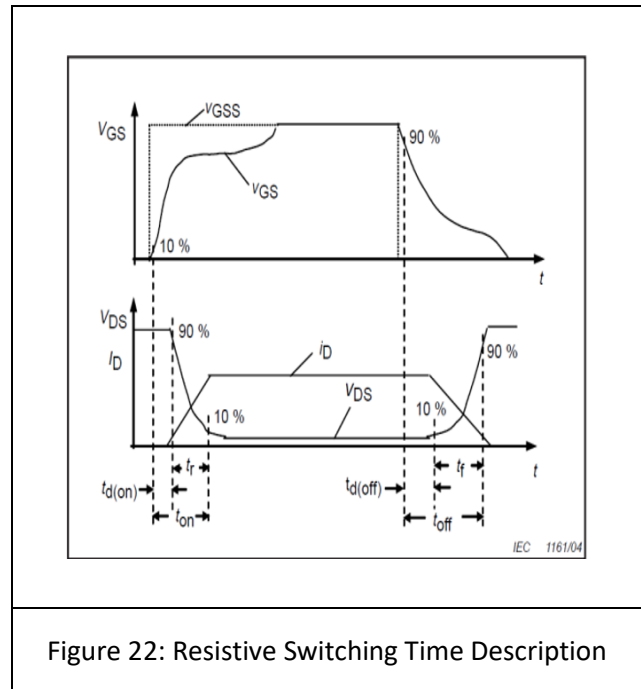


Figure 22: Resistive Switching Time Description

### Test Circuit Schematic

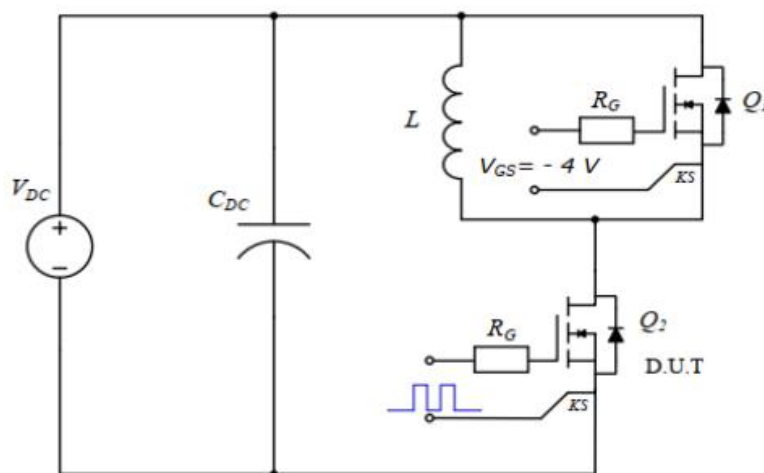
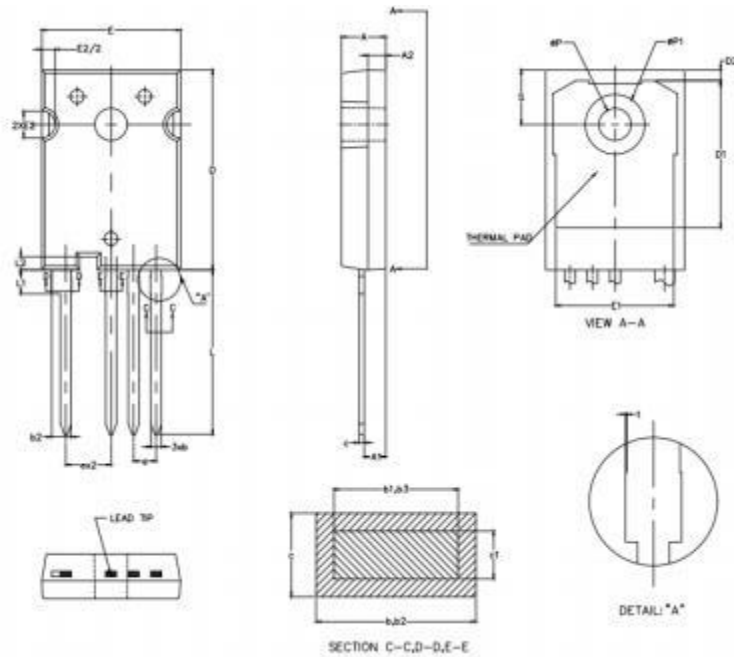


Figure 23: Clamped Inductive Switching Waveform Test Circuit

## Package Dimensions

Package: TO-247-4



SYMBOLS	DIMENSIONS			
	mm		inch	
	MIN.	MAX.	MIN.	MAX.
A	4.90	5.10	0.193	0.201
A1	2.31	2.51	0.091	0.099
A2	1.90	2.10	0.075	0.083
b	1.16	1.26	0.046	0.050
b1	1.15	1.22	0.045	0.048
b2	2.16	2.26	0.085	0.089
b3	2.15	2.22	0.085	0.087
c	0.59	0.66	0.023	0.026
c1	0.58	0.62	0.023	0.024
D	22.40	22.60	0.882	0.890
D1	16.25	16.85	0.640	0.663
D2	1.05	1.35	0.041	0.053
E	15.75	15.90	0.620	0.626
E1	13.26	—	0.552	—
E2	2.90	3.10	0.114	0.122
e	2.54BSC		0.1BSC	
L	18.30	18.60	0.720	0.732
L1	—	2.80	—	0.110
L2	—	1.50	—	0.059
$\phi P$	3.50	3.70	0.138	0.146
$\phi P1$	—	7.40	—	0.291
S	6.05	6.25	0.238	0.246
t	0.00	0.15	0.000	0.006

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